

IN THE SPECIFICATION

Please replace Paragraph [0003] with the following amended paragraph:

[0003] Semiconductor packages ~~which~~ that comprise a leadframe that includes a central platform to which an integrated-chip is connected are known. These types of semiconductor packages are generally fabricated with radiating external electrical connection leads connected at a fixed distance from the central platform and generally connected to the integrated-chip via electrical connection wires.

Please replace Paragraph [0004] with the following amended paragraph:

[0004] These ~~type~~ types of semiconductor ~~package~~ packages although useful, have their shortcomings. One shortcoming is the complexity to fabricate the chip. Accordingly, a need exists to overcome the complexity to ~~fabricated semiconductor~~ fabricate semiconductor packages with lead lines attached to integrated circuits.

Please replace Paragraph [0016] with the following amended paragraph:

[0016] According to the invention, the encapsulation block may comprise a peripheral annular part extending ~~forwards~~ forward, around and at a certain distance from the ~~[[plate, a]]~~ plate. A ring made of a filling material ~~filling~~ fills the space that separates the periphery of the plate from the peripheral annular part.

Please replace Paragraph [0044] with the following amended paragraph:

[0044] This package body 21 comprises a rear wall 22, ~~that~~ which has a rear face 23 and a front face 24, and a forward projecting peripheral wall 25 forming an annular wall.

Please replace Paragraph [0044] with the following amended paragraph:

[0044] This package body 21 comprises a rear wall 22, that which has a rear face 23 and a front face 24, and a forward projecting peripheral wall 25 forming an annular wall.

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10/781,557